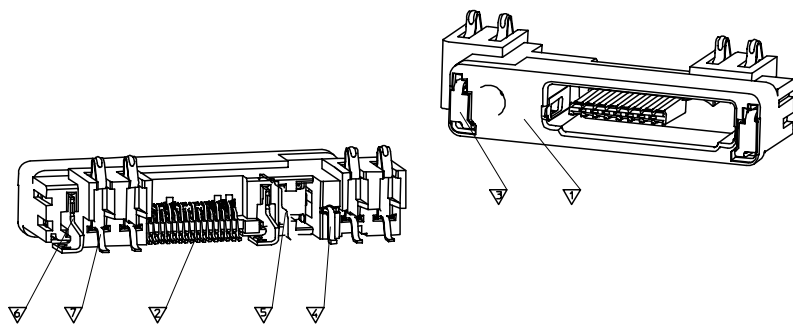
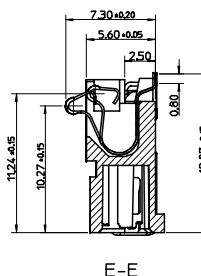




RECOMMENDED PCB LAYOUT



	COMPONENT	DESCRIPTION	QTY
▽	HOUSING	45% GLASS FILLED NYLON 46 (RATED UL94 V-0), COLOUR BLACK,	1
▽	SIGNAL CONTACT	MATERIAL: 0.20 REF. THK. PHOSPHOR BRONZE. PLATING: 127um MIN. NICKEL UNDERCOAT ALL OVER. 0.1um MIN. GOLD OVER 10um MIN. PALLADIUM NICKEL ON CONTACT AREA. 3.0um MIN. TIN IN SOLDER TAIL AREA (ALL SIDES).	16
▽	CHARGER PADS/ SMT RETENTION NAILS	MATERIAL: 0.30 REF. THK. PHOSPHOR BRONZE. PLATING: 127um MIN. NICKEL UNDERCOAT OVERALL. 0.1um MIN. GOLD FLASH OVER 10um MIN. PALLADIUM NICKEL IN CONTACT AREA. 3.0um MIN. Sn IN SOLDER TAIL AREA (ALL SIDES).	2
▽	DC PIN	MATERIAL: 0.65 REF. THK. COPPER ALLOY PLATING: 127um MIN. NICKEL UNDERCOAT ALL OVER. 3-4um NICKEL IN CONTACT AREA. 3.0um MIN. TIN IN SOLDER TAIL AREA.	1
▽	DC BEAM	MATERIAL: 0.28 REF. THK. BERYLLIUM COPPER. PLATING: 0.25um MIN. NICKEL UNDERCOAT ALL OVER. 2-3um NICKEL UNDER 3um MIN SILVER, ONE SIDE ONLY 3.0um MIN. TIN IN SOLDER TAIL AREA (ALL SIDES).	1
▽	LOCKING LATCHES	MATERIAL: 0.30 REF. THK. STAINLESS STEEL. PLATING: 3-5um TIN OVER 127 -250um NICKEL UNDERCOAT ALL OVER.	2
▽	BATTERY CONTACT	MATERIAL: 0.17 REF. THK. PHOSPHOR BRONZE. PLATING: 127um MIN. NICKEL UNDERCOAT OVERALL. 0.10um MIN. GOLD FLASH OVER PALLADIUM-NICKEL (80/20) 1.0-1.5um ON CONTACT AREA. 3.0um MIN. Sn IN SOLDER TAIL AREA.	4

NOTES:

1. COPLANARITY: ALL SMT TAILS TO LIE WITHIN A COPLANARITY BAND OF -0.05 TO -0.15 FROM DATUM 'A'.
SEE COPLANARITY SENSE DIRECTION.
DATUM 'A' IS TO BE TAKEN AS THE PLANE OF A METAL BLOCK ON WHICH DATUM A1 & A2 REST, TAPE AND REEL. SEE DRAWING 5D-91403-005
2. PACKAGING: SEE DRAWING 5D-91403-005
3. LEAD FLATNESS: 0.1 FOR ALL SMT TAILS
4. TEXT TO BE LASER PRINTED
5. GATING VESSTAGE MARK NOT TO PROTRUDE PAST DATUM A
6. TEXT: PART NO./ MX ID/ CAVITY ID, TO BE 10 HIGH AND RAISED 0.1 MAX

[illegible]